



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3) Qualified to AEC-Q101 Standards for High Reliability

Case Material: Molded Plastic, "Green" Molding Compound.

Terminals: Finish - Matte Tin Annealed over Copper Leadframe.

UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020 Terminals Connections: See Diagram

Solderable per MIL-STD-202, Method 208 @3

Weight: 0.013 grams (Approximate)

Features and Benefits

Low On-Resistance Low Input Capacitance Fast Switching Speed Low Input/Output Leakage ESD Protected Gate

Mechanical Data

Case: TSOT26

Product Summary

Device	BV _{DSS}	Rds(on) max	I _{D MAX} T _A = +25°С
01		$0.45\Omega @ V_{GS} = 4.5V$	
Q1 N-Channel	25V	$0.60\Omega @ V_{GS} = 2.7V$	0.68A
		0.73Ω @ V _{GS} = 1.8V	
00		1.1Ω @ V _{GS} = -4.5V	
Q2 P-Channel	-25V	1.5Ω @ V _{GS} = -2.7V	-0.46A
		2.2Ω @ V _{GS} = -1.8V	

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

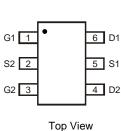
- Backlighting
- DC-DC Converters
- Power Management Functions

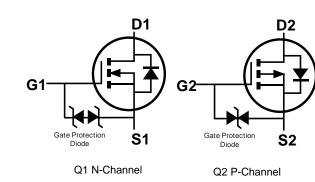
ESD PROTECTED



TSOT26

Top View





Ordering Information (Note 4)

Part Number	Case	Packaging
DMC3730UVT-7	TSOT26	3000 / Tape & Reel
DMC3730UVT-13	TSOT26	10,000 / Tape & Reel

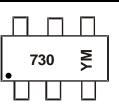
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



 $\begin{array}{l} 730 = \mbox{Product Type Marking Code} \\ YM = \mbox{Date Code Marking} \\ Y \mbox{or} \end{tabular} \\ Y \mbox{or} \end{tabular} \\ T = \end{tabular} \\ M = \mbox{Month (ex: 9 = September)} \end{array}$

Date Code Key

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Year	2017	2018	20	019	2020	2021	1	2022	2023	202	24	2025
Code	E	F		G	Н			J	К	L		М
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

1 of 10



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Unit
Drain-Source Voltage			V _{DSS}	25	-25	V
Gate-Source Voltage	V _{GSS}	±8	±8	V		
Continuous Drain Current (Note 6) N-Channel: V _{GS} = 4.5V P-Channel: V _{GS} = -4.5V	Steady State	T _A = +25°C	ID	0.68	-0.46	А
Maximum Continuous Body Diode Forward Current (Note 6)			Is	0.3	-0.3	А
Pulsed Drain Current (10µs Pulse, Duty Cycle =	I _{DM}	3	-2.5	А		

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	180	°C/W
Total Power Dissipation (Note 6)		PD	0.9	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _θ JA	140	°C/W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	60	C/VV
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

Electrical Characteristics N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Tun	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)	Symbol	IVIIII	Тур	Wax	Unit	Test condition	
Drain-Source Breakdown Voltage	BV _{DSS}	25	-	-	V	V _{GS} = 0V, I _D = 250µA	
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	IDSS	-	-	1.0	μA	$V_{\rm DS} = 20V, V_{\rm GS} = 0V$	
Gate-Source Leakage	I _{GSS}		-	±10	μA	$V_{DS} = 20V, V_{dS} = 0V$ $V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)	IGSS	_	-	10	μΛ	$v_{\rm GS} = \pm \delta v, v_{\rm DS} = \delta v$	
Gate Threshold Voltage	V _{GS(TH)}	0.45	0.7	1.1	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
		-	0.28	0.45		$V_{GS} = 4.5V, I_D = 0.5A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	-	0.33	0.60	Ω	$V_{GS} = 2.7V, I_D = 0.25A$	
		-	0.39	0.73		$V_{GS} = 1.8V, I_D = 0.1A$	
Diode Forward Voltage	V _{SD}	-	0.75	1.2	V	$V_{GS} = 0V, I_{S} = 0.5A$	
DYNAMIC CHARACTERISTICS (Note 8)					•		
Input Capacitance	Ciss	-	50	-	pF		
Output Capacitance	Coss	-	28	-	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	9	-	pF	1 = 1.00012	
Gate Resistance	Rg	-	64	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	-	1.64	-	nC		
Gate-Source Charge	Q _{gs}	-	0.38	-	nC	$V_{DS} = 5V, I_D = 0.5A,$ $V_{GS} = 4.5V$	
Gate-Drain Charge	Q _{gd}	-	0.45	-	nC	$v_{GS} = 4.5 v$	
Turn-On Delay Time	t _{D(ON)}	-	3	-	ns		
Turn-On Rise Time	t _R	-	8	-	ns	$V_{GS} = 4.5V, V_{DS} = 6V,$	
Turn-Off Delay Time	t _{D(OFF)}	-	17	-	ns	$R_g = 50\Omega, I_D = 0.5A$	
Turn-Off Fall Time	tF	-	13	-	ns	1 [~]	



Electrical Characteristics P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

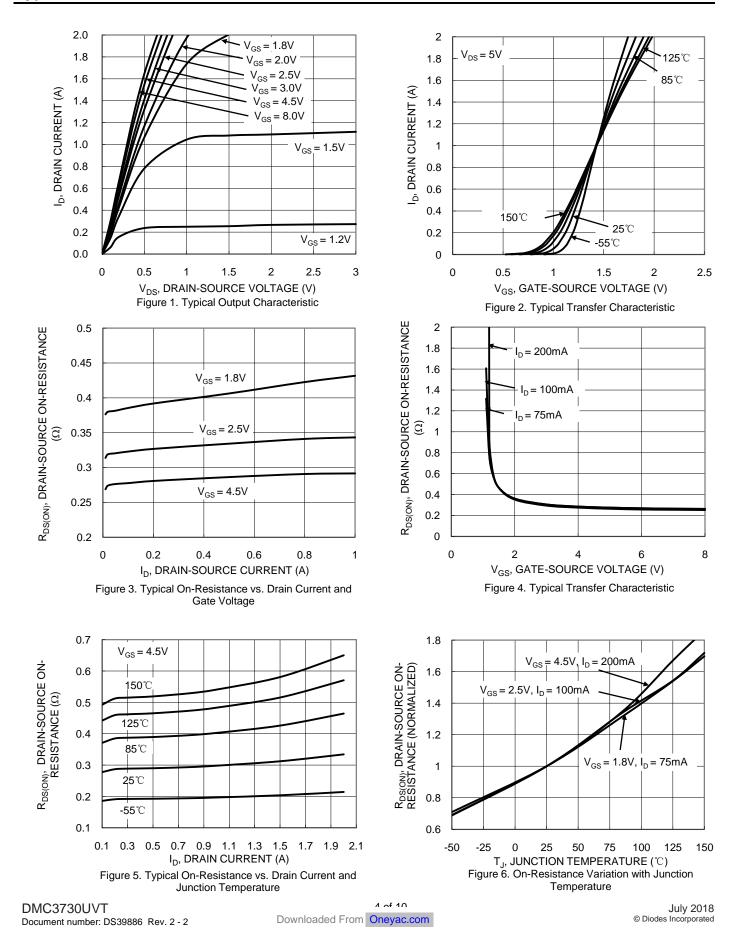
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-25	-	-	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	I _{DSS}	-	-	-1.0	μA	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	-	-	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-0.5	-0.8	-1.1	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
		-	0.65	1.1		V _{GS} = -4.5V, I _D = -0.5A
Static Drain-Source On-Resistance	R _{DS(ON)}	-	0.80	1.5	Ω	V _{GS} = -2.7V, I _D = -0.25A
		-	1.0	2.2		V _{GS} = -1.8V, I _D = -0.1A
Diode Forward Voltage	V _{SD}	-	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -0.5A$
DYNAMIC CHARACTERISTICS (Note 8)						-
Input Capacitance	Ciss	-	63	-	pF	
Output Capacitance	C _{oss}	-	34	-	pF	V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	-	10	-	pF	1 = 1.00012
Gate Resistance	Rg	-	178	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge	Qg	-	1.1	-	nC	
Gate-Source Charge	Q _{gs}	-	0.32	-	nC	$V_{DS} = -5V, I_D = -0.25A,$
Gate-Drain Charge	Q _{gd}	-	0.25	-	nC	$V_{GS} = -4.5V$
Turn-On Delay Time	t _{D(ON)}	-	7	-	ns	
Turn-On Rise Time	t _R	-	9	-	ns	$V_{GS} = -4.5V, V_{DS} = -6V,$
Turn-Off Delay Time	t _{D(OFF)}	-	55	-	ns	$R_{g} = 50\Omega, I_{D} = -0.5A$
Turn-Off Fall Time	tF	-	35	-	ns	1 -

Notes:

Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.

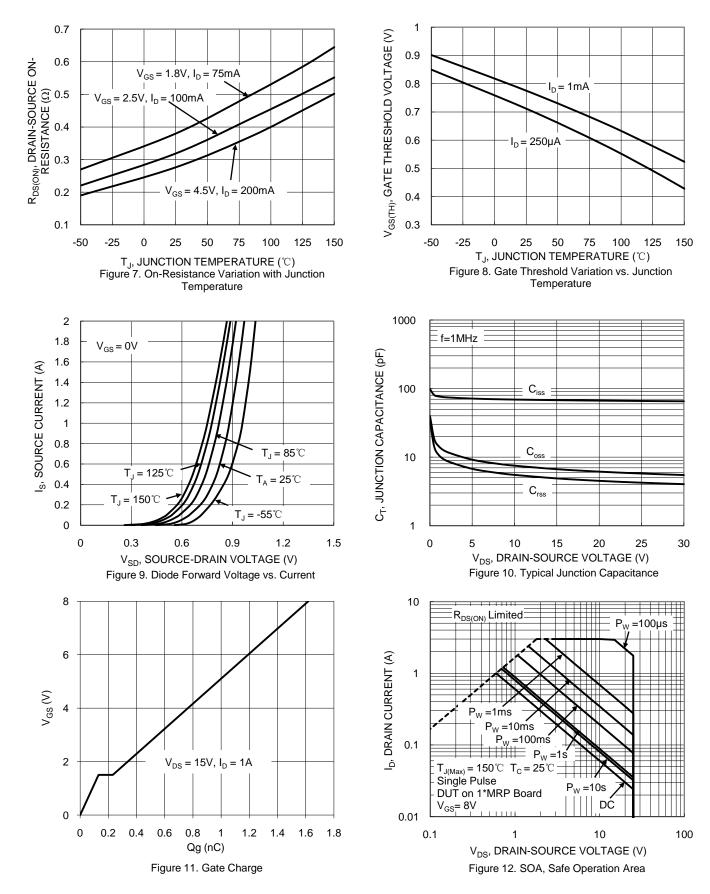


Typical Characteristics - N-CHANNEL



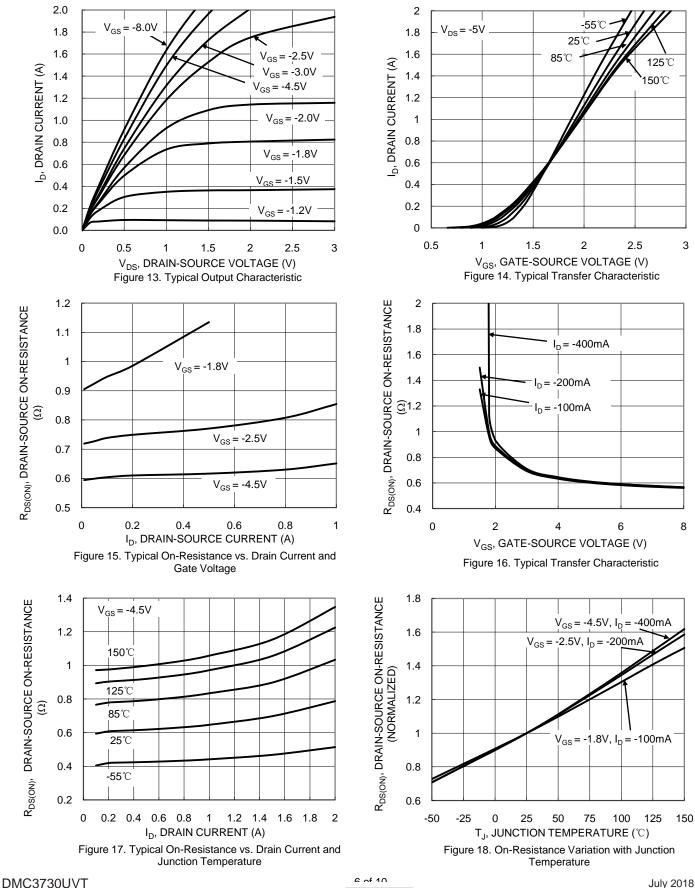


Typical Characteristics - N-CHANNEL (Cont.)





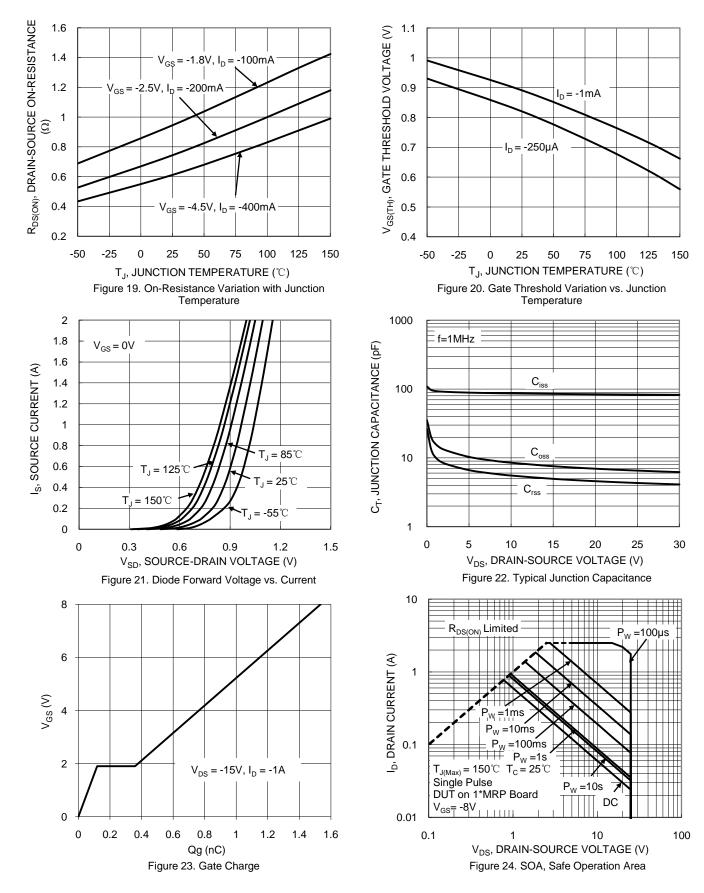
Typical Characteristics - P-CHANNEL



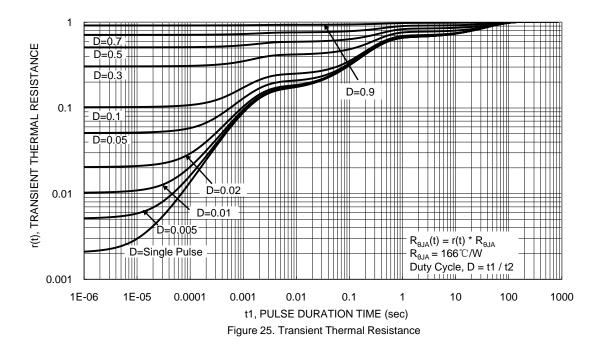
Document number: DS39886 Rev. 2 - 2



Typical Characteristics - P-CHANNEL (Cont.)



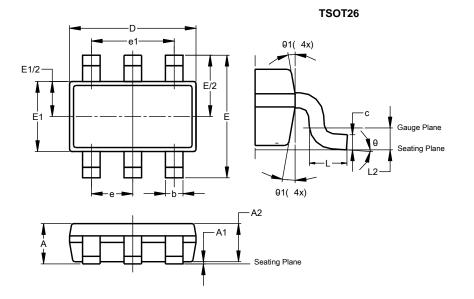






Package Outline Dimensions

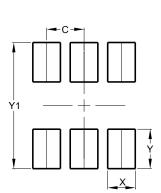
Please see http://www.diodes.com/package-outlines.html for the latest version.



TSOT26								
Dim	Min	Max	Тур					
Α	-	1.00	-					
A1	0.010	0.100	-					
A2	0.840	0.900	-					
D	2.800	3.000	2.900					
ш	2	.800 BS	С					
E1	1.500	1.700	1.600					
b	0.300	0.450	-					
С	0.120	0.200	-					
е	0.950 BSC							
e1	1	.900 BS	С					
1	0.30	0.50	-					
L2	0.250 BSC							
θ	0°	8°	4°					
θ1	4°	12°	-					
A	II Dimen	sions in	mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.950
Х	0.700
Y	1.000
Y1	3.199

TSOT26



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